November 2014



FDB9409_F085

N-Channel PowerTrench® MOSFET

40 V, 80 A, 3.5 mΩ

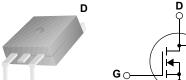
Features

- Typical $R_{DS(on)}$ = 2.5 mΩ at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{q(tot)}$ = 43 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- PowerTrain Management
- Solenoid and Motor Drivers
- Integrated Starter/Alternator
- Primary Switch for 12V Systems





TO-263 FDB SERIES

For current package drawing, please refer to the Fairchild website at https://www.fairchildsemi.com/package-drawings/TO/TO263A02.pdf

MOSFET Maximum Ratings $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-to-Source Voltage		40	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Drain Current - Continuous (V_{GS} =10) (Note 1) T_C = 25°C Pulsed Drain Current T_C = 25°C		80	А
ID			See Figure 4	_ ^
E _{AS}	Single Pulse Avalanche Energy (Note 2)		70	mJ
D	Power Dissipation		94	W
P_{D}	Derate Above 25°C		0.63	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.6	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

Notes

- 1: Current is limited by bondwire configuration.
- 2: Starting $T_J = 25^{\circ}C$, L = 34uH, $I_{AS} = 64A$, $V_{DD} = 40V$ during inductor charging and $V_{DD} = 0V$ during time in avalanche.
- 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,JC} is guaranteed by design, while R_{0,JA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB9409	FDB9409_F085	D2-PAK(TO-263)	330mm	24mm	800 units

Units

Max.

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Parameter

Off Ch	Off Characteristics							
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40	-	-	V		
1	Drain-to-Source Leakage Current	$V_{DS} = 40V$, $T_{J} = 25^{\circ}C$	-	-	1	μΑ		
IDSS	Dialii-to-Source Leakage Current	$V_{GS} = 0V$ $T_J = 175^{\circ}C$ (1	Note 4) -	-	1	mA		
I_{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA		

Test Conditions

Min.

Тур.

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.0	4.0	V
R _{DS(on)} Drain to Source On Resistance	Drain to Source On Registance	I _D = 80A,	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	2.5	3.5	mΩ
	V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	4.2	5.9	mΩ	

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0V, f = 1MHz		-	2980	-	pF
C _{oss}	Output Capacitance			-	788	-	pF
C _{rss}	Reverse Transfer Capacitance			-	45	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.2	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	$V_{GS} = 0 \text{ to } 10V$ $V_{DD} = 32V$		-	43	56	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$ $I_D = 80A$		-	5	7	nC
Q_{gs}	Gate-to-Source Gate Charge			-	15.5	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge			-	10	-	nC

Switching Characteristics

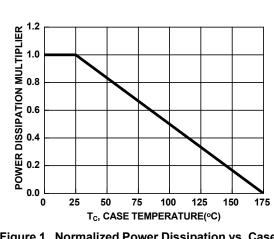
t _{on}	Turn-On Time		-	-	193	ns
t _{d(on)}	Turn-On Delay		-	17	-	ns
t _r	Rise Time	V_{DD} = 20V, I_{D} = 80A, V_{GS} = 10V, R_{GEN} = 6Ω	-	90	-	ns
t _{d(off)}	Turn-Off Delay		-	24	-	ns
t _f	Fall Time		-	10	-	ns
t _{off}	Turn-Off Time		-	-	50	ns

Drain-Source Diode Characteristics

V _{SD} S	Source-to-Drain Diode Voltage	I_{SD} =80A, V_{GS} = 0V	-	-	1.25	V
	Source-to-Drain blode voltage	I_{SD} = 40A, V_{GS} = 0V	-	-	1.25 1.2 71 62	V
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	54	71	ns
Q_{rr}	Reverse-Recovery Charge	V _{DD} =32V	ı	47	62	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.



Typical Characteristics

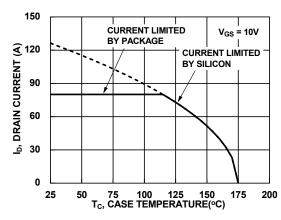
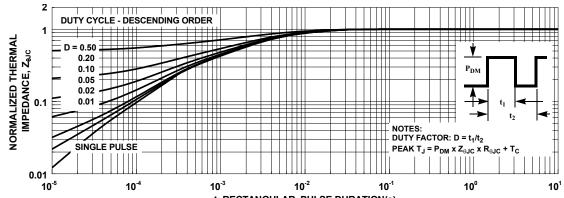


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs.

Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

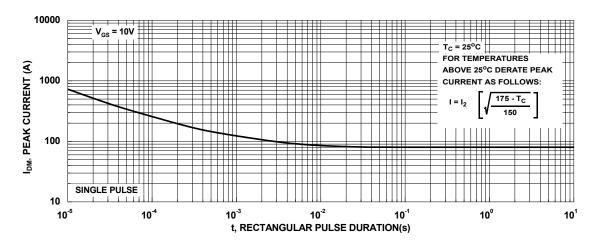


Figure 4. Peak Current Capability

Typical Characteristics

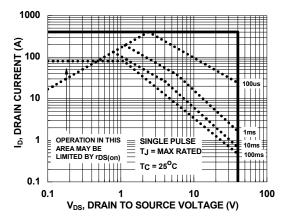


Figure 5. Forward Bias Safe Operating Area

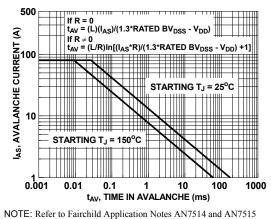


Figure 6. Unclamped Inductive Switching Capability

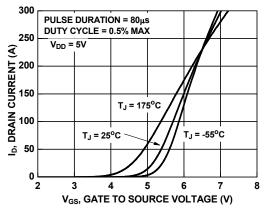


Figure 7. Transfer Characteristics

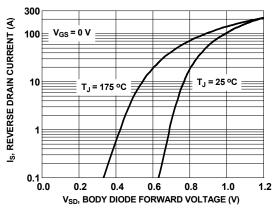


Figure 8. Forward Diode Characteristics

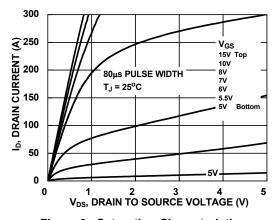


Figure 9. Saturation Characteristics

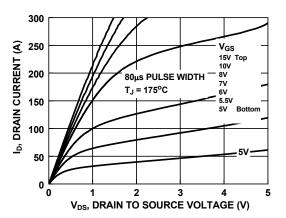


Figure 10. Saturation Characteristics

Typical Characteristics

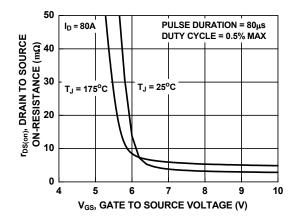


Figure 11. R_{DSON} vs. Gate Voltage

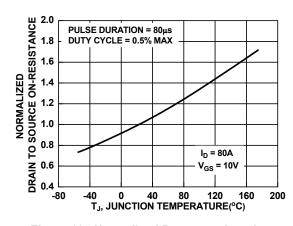


Figure 12. Normalized R_{DSON} vs. Junction Temperature

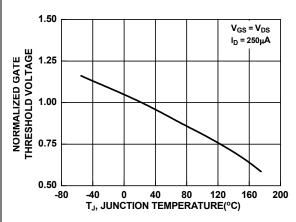


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

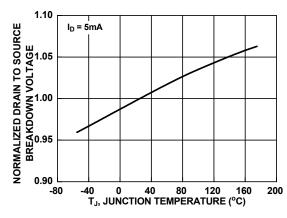


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

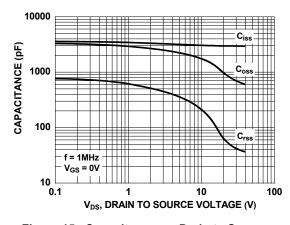


Figure 15. Capacitance vs. Drain to Source Voltage

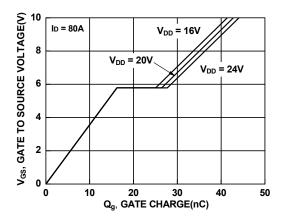


Figure 16. Gate Charge vs. Gate to Source Voltage





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AX-CAP®* Global Power ResourceSM
BitSiC™ GreenBridge™

Build it Now™ Green FPS^{TM} CorePLUS™ Green FPS^{TM} e-Series™
CorePOWER™ $Gmax^{TM}$

 $\begin{array}{lll} & & & & & & & & & & & \\ CROSSVOLT^{\text{TM}} & & & & & & & \\ CTL^{\text{TM}} & & & & & & & \\ Current & Transfer & Logic^{\text{TM}} & & & & & \\ & & & & & & & & \\ \end{array}$

DEUXPEED® Marking Small Speakers Sound Louder

 Dual Cool™
 and Better™

 EcoSPARK®
 MegaBuck™

 EfficentMax™
 MICROCOUPLER™

 ESBC™
 MicroFET™

MicroFET™ MicroPak™ MicroPak2™ MillerDrive™ MotionMax™ MotionGrid®

FACT Quiet Series™ MotionGrid'
FACT® MTi®
FAST® MTx®
FastvCore™ MVN®
FETBench™ mWSaver®
FPS™ OptoHiT™

® PowerTrench® PowerXS™

Programmable Active Droop™

QFĒT[®]
QS™
Quiet Series™
RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™
Sync-Lock™

SYSTEM ®*
GENERAL
TinyBoost®
TinyBock®
TinyCalc™
TinyLogic®
TiNYOPTO™
TinyPower™
TinyPower™
TinyPWM™
TinyWire™
TranSiC™
TriFault Detect™
TRUECURRENT®*

µSerDes™

SerDes[™]
UHC[®]
Ultra FRFET[™]
UniFET[™]

Ultra FRFET™ UniFET™ VCX™ VisualMax™ VoltagePlus™ XS™ Xsens™ 仙童™

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

Fairchild[®]

Fairchild Semiconductor®

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT http://www.fairchildsemi.com. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used here in

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

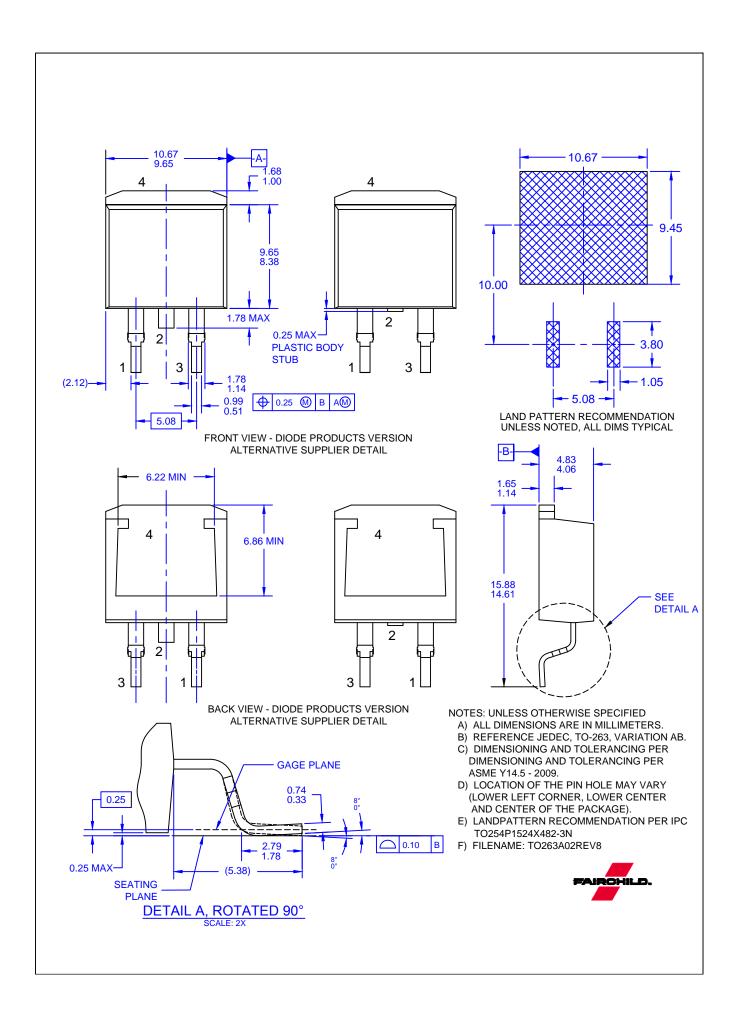
Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary First Production		Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed Full Production		Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete Not In Production		Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 171







TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ F-PFS™ AttitudeEngine™ FRFET®

Global Power ResourceSM Awinda[®] AX-CAP®*

GreenBridge™ BitSiC™ Green FPS™ Build it Now™ Green FPS™ e-Series™

CorePLUS™ Gmax™ CorePOWER™ $\mathsf{GTO}^{\mathsf{TM}}$ CROSSVOLT™ IntelliMAX™ CTL™ ISOPLANAR™

Current Transfer Logic™ Making Small Speakers Sound Louder

DEUXPEED® and Better™ Dual Cool™ MegaBuck™ EcoSPARK® MIČROCOUPLER™ EfficientMax™ MicroFET™

MicroPak™ MicroPak2™ MillerDrive™ MotionMax™ Fairchild Semiconductor®

MotionGrid® FACT Quiet Series™ MTi[®] FACT[®] MTx® FastvCore™ MVN® FETBench™ mWSaver® FPS™ OptoHiT™ OPTOLOGIC® OPTOPLANAR®

Power Supply WebDesigner™ PowerTrench®

PowerXSTI

Programmable Active Droop™ OFFT

QS™ Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM® STEALTH™ SuperFET® SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS® SyncFET™ Sync-Lock™

SYSTEM SYSTEM TinyBoost[®] TinyBuck[®] TinyCalc™ TinyLogic[®] TINYOPTO™

TinvPower™ TinyPWM™ TinyWire™ TranSiC™ TriFault Detect™

TRUECURRENT®* սSerDes™

UHC Ultra FRFET™

UniFET™ VCX™ VisualMax™ VoltagePlus™ XSTM. Xsens™ 仙童®

ESBC™

-®

Fairchild®

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR <u>AIRCHILDSEMI.COM.</u> FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application - including life critical medical equipment - where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com,

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Deminition of Terms		
Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev 177

^{*} Trademarks of System General Corporation, used under license by Fairchild Semiconductor.